

Data Sheet October 1998 File Number 1443.2

# 15A, 150V, 0.150 Ohm, N-Channel Power MOSFETs

These are N-Channel enhancement mode silicon gate power field effect transistors designed for applications such as switching regulators, switching converters, motor drivers, relay drivers and drivers for high power bipolar switching transistors requiring high speed and low gate drive power. These types can be operated directly from integrated circuits.

Formerly developmental type TA09195.

# **Ordering Information**

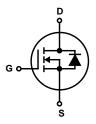
PART NUMBER	PACKAGE	BRAND		
RFP15N15	TO-220AB	RFP15N15		

NOTE: When ordering, use the entire part number.

### **Features**

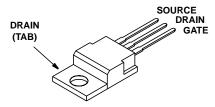
- 15A, 150V
- $r_{DS(ON)} = 0.150\Omega$
- · Related Literature
  - TB334 "Guidelines for Soldering Surface Mount Components to PC Boards"

## Symbol



# **Packaging**

#### JEDEC TO-220AB



### **RFP15N15**

# **Absolute Maximum Ratings** $T_C = 25^{\circ}C$ , Unless Otherwise Specified

	RFP15N15	UNITS
Drain to Source Voltage (Note 1)	150	V
Drain to Gate Voltage (RGS = $20k\Omega$ ) (Note 1)	150	V
Continuous Drain Current	15 40	A A
Gate to Source Voltage	±20	V
Maximum Power Dissipation	75 0.6	W W/ <sup>o</sup> C
Operating and Storage Temperature	-55 to 150	oC
Maximum Temperature for Soldering Leads at 0.063in (1.6mm) from Case for 10s	300 260	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

#### NOTE:

1.  $T_J = 25^{\circ}C$  to  $125^{\circ}C$ .

# **Electrical Specifications** $T_C = 25^{\circ}C$ , Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Drain to Source Breakdown Voltage	BV <sub>DSS</sub>	$I_D = 250 \mu A, V_{GS} = 0 V$	150	-	-	V
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}$ , $I_D = 250\mu A$	2	-	4	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = Rated BV <sub>DSS</sub> , V <sub>GS</sub> = 0V	-	-	1	μА
		$V_{DS} = 0.8 \text{ x Rated BV}_{DSS}, V_{GS} = 0V, T_{C} = 125^{\circ}C$			25	μА
Gate to Source Leakage Current	I <sub>GSS</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±100	nA
Drain to Source On Resistance (Note 2)	r <sub>DS(ON)</sub>	I <sub>D</sub> = 15A, V <sub>GS</sub> = 10V (Figures 6, 7)	-	-	0.150	Ω
Drain to Source On Voltage (Note 2)	V <sub>DS(ON)</sub>	I <sub>D</sub> = 15A, V <sub>GS</sub> = 10V	-	-	2.25	V
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1MHz (Figure 9)	-	-	1700	pF
Output Capacitance	C <sub>OSS</sub>		-	-	750	pF
Reverse-Transfer Capacitance	C <sub>RSS</sub>			-	350	pF
Turn-On Delay Time	t <sub>d(ON)</sub>	$V_{DD}$ = 75V, $I_{D}$ $\approx$ 7.5A, $R_{G}$ = 50 $\Omega$ , $V_{GS}$ = 10V $R_{L}$ = 9.9 $\Omega$ , (Figures 10, 11, 12)	-	50	75	ns
Rise Time	t <sub>r</sub>		-	150	225	ns
Turn-Off Delay Time	t <sub>d(OFF)</sub>		-	185	280	ns
Fall Time	t <sub>f</sub>			125	190	ns
Thermal Resistance Junction-to-Case			-	-	1.67	°C/W

### **Source to Drain Diode Specifications**

PARAMETERS	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage (Note 2)	V <sub>SD</sub>	I <sub>SD</sub> = 7.5A	-	-	1.4	V
Reverse Recovery Time	t <sub>rr</sub>	$I_{SD} = 4A$ , $dI_{SD}/dt = 100A/\mu s$	-	200	-	ns

### NOTES:

- 2. Pulse test: width  $\leq 300 \mu s$ , duty cycle  $\leq 2\%$ .
- 3. Repetitive rating: pulse width is limited by maximum junction temperature.

# Typical Performance Curves Unless Otherwise Specified

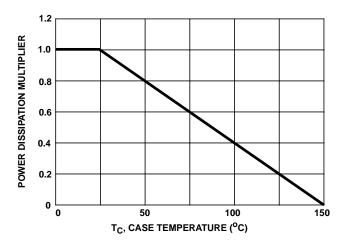


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

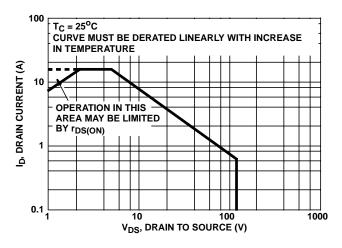


FIGURE 3. FORWARD BIAS SAFE OPERATING AREA

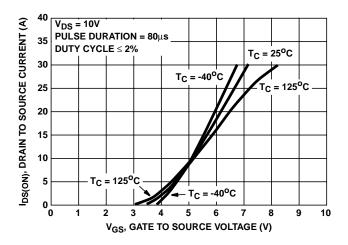


FIGURE 5. TRANSFER CHARACTERISTICS

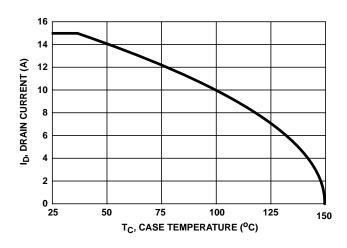


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

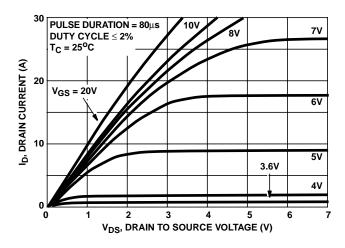


FIGURE 4. SATURATION CHARACTERISTICS

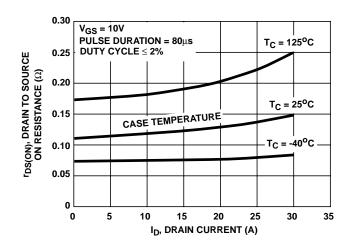


FIGURE 6. DRAIN TO SOURCE ON RESISTANCE VS DRAIN CURRENT

# Typical Performance Curves Unless Otherwise Specified (Continued)

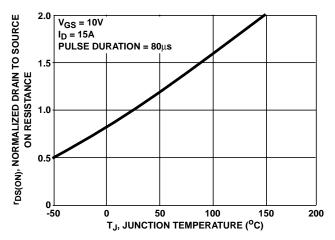


FIGURE 7. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

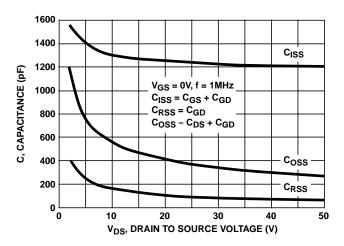


FIGURE 9. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE

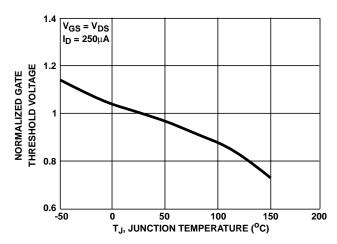
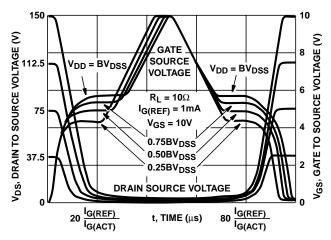


FIGURE 8. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE



NOTE: Refer toIntersil Application Notes AN7254 and AN7260.

FIGURE 10. NORMALIZED SWITCHING WAVEFORMS FOR CONSTANT GATE CURRENT

### Test Circuits and Waveforms

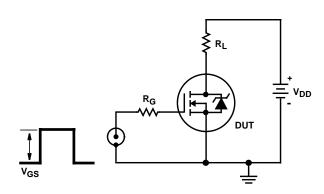


FIGURE 11. SWITCHING TIME TEST CIRCUIT

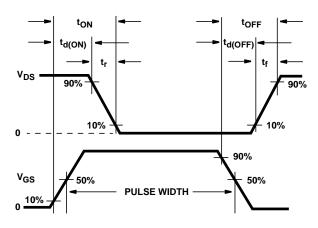


FIGURE 12. RESISTIVE SWITCHING WAVEFORMS

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